



# SOT527-1

plastic thermal enhanced thin shrink small outline package;  
20 leads; body width 4.4 mm; exposed die pad

25 May 2018

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HTSSOP20
<b>Package type industry code</b>	HTSSOP20
<b>Package style descriptive code</b>	HTSSOP (thermal enhanced thin shrink small outline package)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-153
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	2-11-2005
<b>Manufacturer package code</b>	SOT527

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	6.4	6.5	6.6	mm
package width	4.3	4.4	4.5	mm
seated height	-	1.1	-	mm
package height	0.8	0.9	0.95	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	20	-	A/A

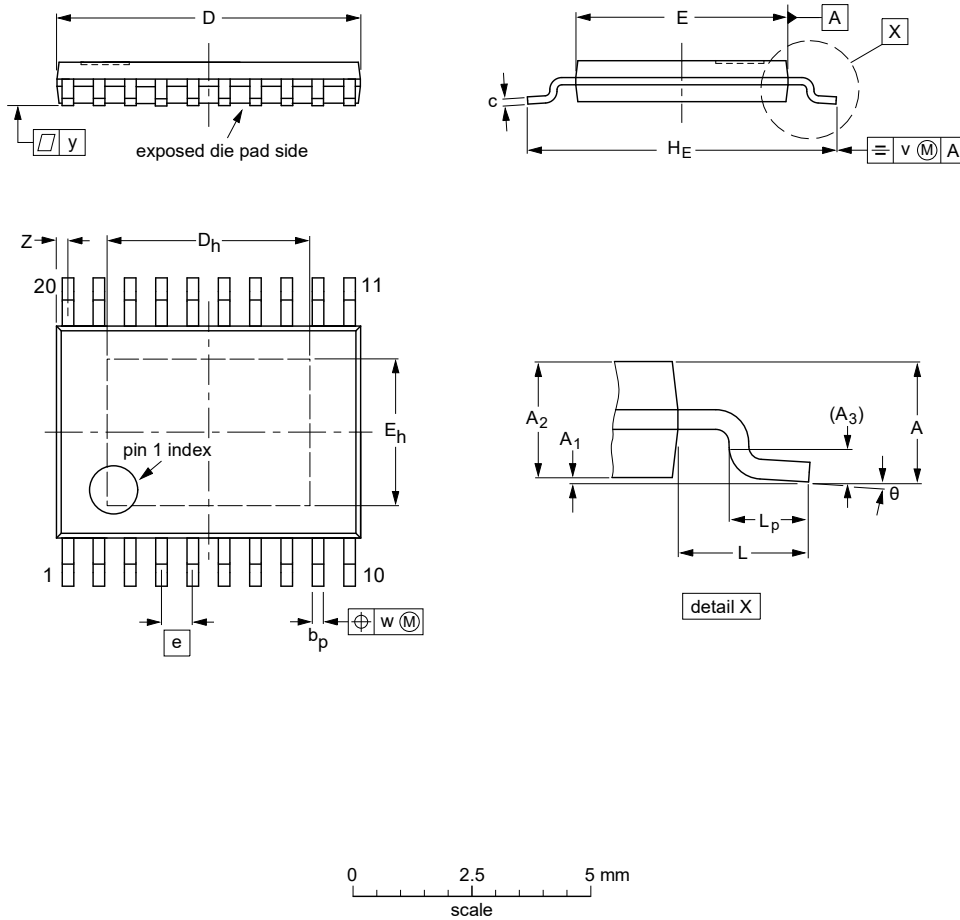


plastic thermal enhanced thin shrink small outline package; 20 leads; body width 4.4 mm; exposed die pad

## 2. Package outline

HTSSOP20: plastic thermal enhanced thin shrink small outline package; 20 leads; body width 4.4 mm; exposed die pad

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(2)</sup>	E <sub>h</sub>	e	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sup>(1)</sup>	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.20 0.09	6.6 6.4	4.3 4.1	4.5 4.3	3.1 2.9	0.65	6.6 6.2	1	0.75 0.50	0.2	0.13	0.1	0.5 0.2	8° 0°

**Notes**

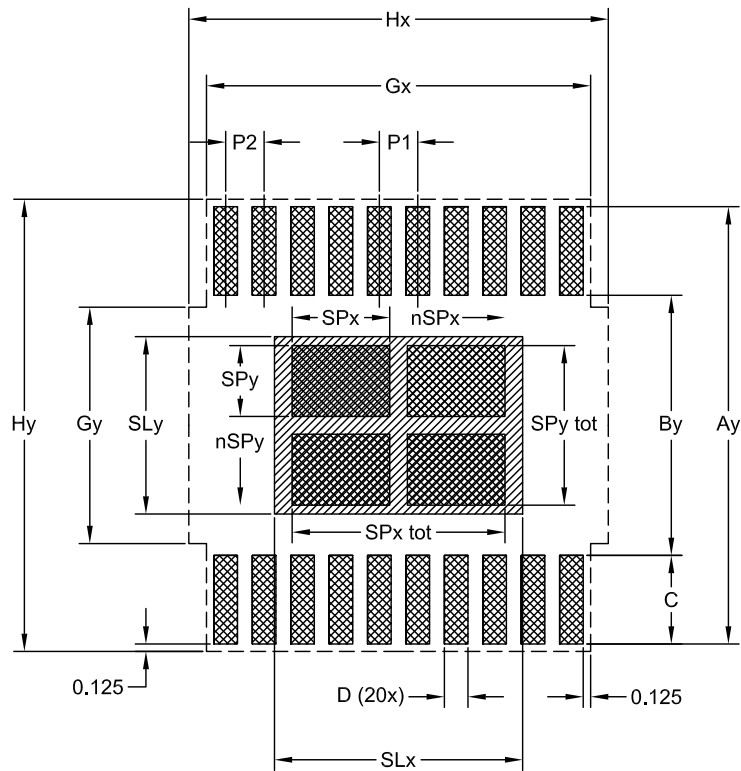
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT527-1		MO-153				03-04-07 05-11-02

Fig. 1. Package outline HTSSOP20 (SOT527-1)

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### 3. Soldering



Recommended stencil thickness 0.125 or 0.15

- solder land
- solder land plus solder paste
- occupied area

Dimensions in mm													
		Hx	Hy	nSPx	nSPy								
		7.100	7.650	2	2								
P1	P2	Ay	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy
0.650	0.650	7.400	4.400	1.500	0.400	4.200	3.000	3.600	2.700	1.650	1.200	6.500	4.000

Fig. 2. Reflow soldering footprint for HTSSOP20 (SOT527-1)

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## 4. Legal information

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